

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Go OTANI</td> <td>05/24/2013</td> </tr> <tr> <td>Yusuke NAKAI</td> <td>05/24/2013</td> </tr> </tbody> </table>		Name	Execution Date	Go OTANI	05/24/2013	Yusuke NAKAI	05/24/2013
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Go OTANI	05/24/2013						
Yusuke NAKAI	05/24/2013						
RECEIVING PARTY DATA							
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Postal Code:	100-8253						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13990183</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13990183		
Property Type	Number						
Application Number:	13990183						
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Signature:	/Mary Jane Boswell/						
Date:	05/29/2013						
Total Attachments: 2 source=056819-5064_Assignment-05292013#page1.tif source=056819-5064_Assignment-05292013#page2.tif							

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12P00126-05  
OSP 48095  
vs 4/2/13

ATTORNEY DOCKET NO.: 056819-5020  
SOLE/JOINT INVENTION  
(U.S. Rights Only)

**ASSIGNMENT**

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

**METHOD FOR PREPARING ARTICLE HAVING UNEVEN MICROSTRUCTURE ON SURFACE THEREOF**

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on \_\_\_\_\_, (Application No. \_\_\_\_\_); and

WHEREAS, **Mitsubishi Rayon Co., Ltd.** a corporation of Japan, whose post office address is **1-1, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-8253 Japan** (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parenthesis (Application No. \_\_\_\_\_, filed \_\_\_\_\_) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

<b>Full Name of Sole or First Assignor</b> Go OTANI	Assignor's Signature <i>Go Otani</i>	Date May 24, 2013
Address c/o Corporate Research Laboratories, Mitsubishi Rayon Co., Ltd., 20-1, Miyuki-cho, Otake-shi, Hiroshima 739-0693 Japan		Citizenship Japan
<b>Full Name of Second Assignor</b> Yusuke NAKAI	Assignor's Signature <i>Yusuke NAKAI</i>	Date May 24, 2013
Address c/o Corporate Research Laboratories, Mitsubishi Rayon Co., Ltd., 20-1, Miyuki-cho, Otake-shi, Hiroshima 739-0693 Japan		Citizenship Japan
Names of additional inventors attached <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No		

12P00126- US  
 05P48095  
 us 1/2

<b>Full Name of Third Assignor</b> Satoru OZAWA	<b>Assignor's Signature</b> Satoru OZAWA	<b>Date</b> May 24, 2013
<b>Address</b> c/o Corporate Research Laboratories, Mitsubishi Rayon Co., Ltd., 20-1, Miyuki-cho, Otake-shi, Hiroshima 739-0693 Japan		<b>Citizenship</b> Japan
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<b>Full Name of Fifth Assignor</b>	<b>Assignor's Signature</b>	<b>Date</b>
<b>Address</b>		<b>Citizenship</b>
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<b>Address</b>		<b>Citizenship</b>
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<b>Address</b>		<b>Citizenship</b>
<b>Full Name of Eighth Assignor</b>	<b>Assignor's Signature</b>	<b>Date</b>
<b>Address</b>		<b>Citizenship</b>
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<b>Address</b>		<b>Citizenship</b>
<b>Full Name of Tenth Assignor</b>	<b>Assignor's Signature</b>	<b>Date</b>
<b>Address</b>		<b>Citizenship</b>
<b>Full Name of Eleventh Assignor</b>	<b>Assignor's Signature</b>	<b>Date</b>
<b>Address</b>		<b>Citizenship</b>
<b>Names of additional inventors attached</b> <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		

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